1.6x0.8mm SMD CHIP LED LAMP



ATTENTION
OBSERVE PRECAUTIONS
FOR HANDLING
ELECTROSTATIC
DISCHARGE
SENSITIVE
DEVICES

APHK1608VGC

GREEN

Features

- •1.6mmx0.8mm SMT LED, 0.7mm THICKNESS.
- •LOW POWER CONSUMPTION.
- •WIDE VIEWING ANGLE.
- •IDEAL FOR BACK LIGHT AND INDICATOR.
- •VARIOUS COLORS AND LENS TYPES AVAILABLE.
- •PACKAGE: 2000PCS/REEL.
- •RoHS COMPLIANT.

Description

The Green source color devices are made with InGaN on SiC Light Emitting Diode.

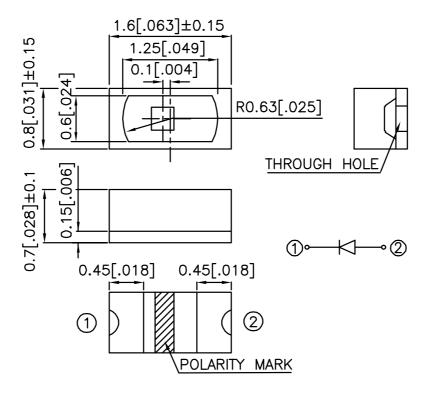
Static electricity and surge damage the LEDS.

It is recommended to use a wrist band or

anti-electrostatic glove when handling the LEDs.

All devices, equipment and machinery must be electrically grounded.

Package Dimensions



Notes:

- 1. All dimensions are in millimeters (inches).
- 2. Tolerance is $\pm 0.1 (0.004")$ unless otherwise noted.
- 3. Specifications are subject to change without notice.

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 APPROVED: J. Lu
 CHECKED: Allen Liu
 DRAWN; Y.W.WANG
 ERP:1204000053

Selection Guide

Part No.	Dice	Lens Type	lv (mcd) @ 20mA		Viewing Angle
			Min.	Тур.	201/2
APHK1608VGC	GREEN (InGaN)	WATER CLEAR	70	180	90°

Note

Electrical / Optical Characteristics at Ta=25°C

Symbol	Parameter	Device	Тур.	Max.	Units	Test Conditions
λpeak	Peak Wavelength	Green	520		nm	IF=20mA
λD	Dominant Wavelength	Green	525		nm	IF=20mA
Δλ1/2	Spectral Line Half-width	Green	38		nm	IF=20mA
С	Capacitance	Green	45		pF	VF=0V;f=1MHz
VF	Forward Voltage	Green	3.5	4.5	V	IF=20mA
lr	Reverse Current	Green		10	uA	VR = 5V

Absolute Maximum Ratings at Ta=25°C

Parameter	Green	Units
Power dissipation	105	mW
DC Forward Current	30	mA
Peak Forward Current [1]	150	mA
Reverse Voltage	5	V
Operating / Storage Temperature	rature -40°C To +85°C	

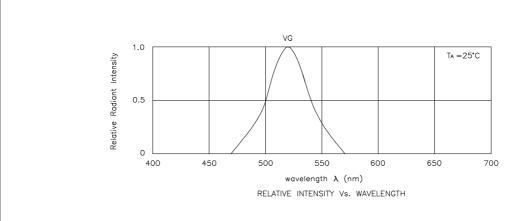
Note

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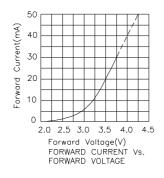
 $^{1.\,\}theta1/2$ is the angle from optical centerline where the luminous intensity is 1/2 the optical centerline value.

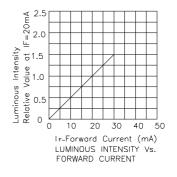
^{1. 1/10} Duty Cycle, 0.1ms Pulse Width.

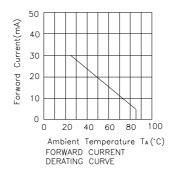


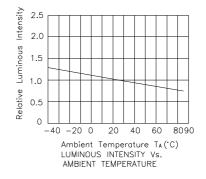
Green

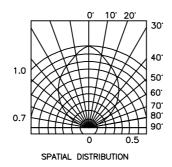
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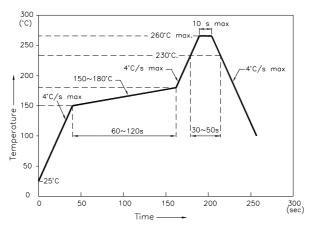


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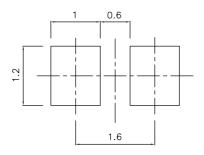
APHK1608VGC

Reflow Soldering Profile For Lead-free SMT Process.

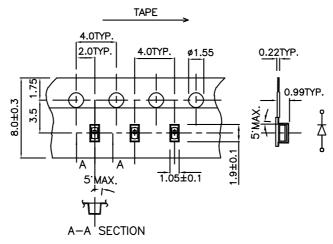


- NOTES: 1.We recommend the reflow temperature 245°C(\pm / \pm 5°C).The maximum soldering temperature should be limited to 260°C.
 - 2.Don't cause stress to the epoxy resin while it is exposed to high temperature.
 - 3. Number of reflow process shall be 2 times or less.

Recommended Soldering Pattern (Units: mm)



Tape Specifications (Units: mm)



If special sorting is required (e.g. binning based on forward voltage, luminous intensity, or wavelength), the typical accuracy of the sorting process is as follows:

- 1. Wavelength: +/-1nm
- 2. Luminous Intensity: +/-15%
- 3. Forward Voltage: +/-0.1V

Note: Accuracy may depend on the sorting parameters.

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